

RA320 SERIES

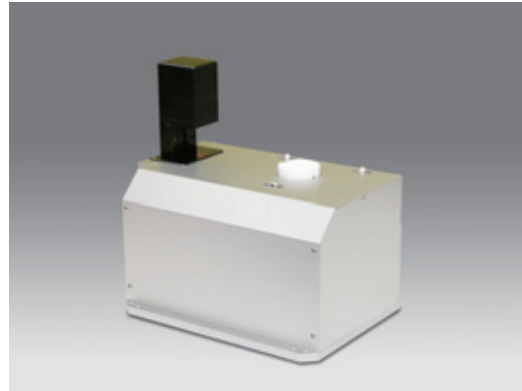


Photo: RA320-C22-L101

The aligner (RA320 SERIES) has the Z-axis and X-axis mechanisms for compensating the wafer position in addition to the θ axis. This is a small and lightweight type to reduce the installation footprint. Various kinds of wafer alignment operations are available according to the type of non-contact optical sensors.

Features

- Handling of transparent objects (glass), laminate, and notch-less wafers (L type)
- Small type and lightweight
- Small footprint

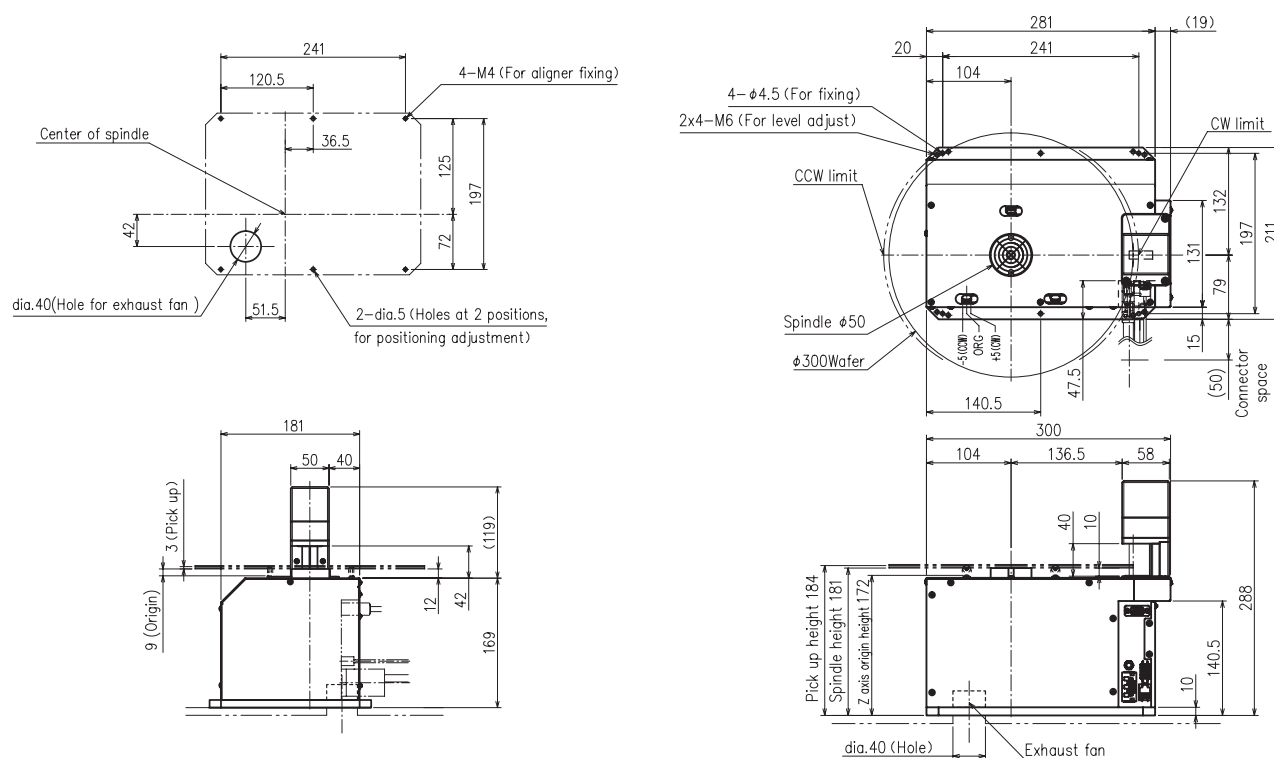
Main specifications

Wafer size	Positioning accuracy		Positioning interval Note 1
	Angle accuracy Note 1	Center accuracy	
ϕ 100 mm to ϕ 300 mm	$\pm 0.05^\circ$ to $\pm 0.2^\circ$	± 0.1 mm	Average 5 sec

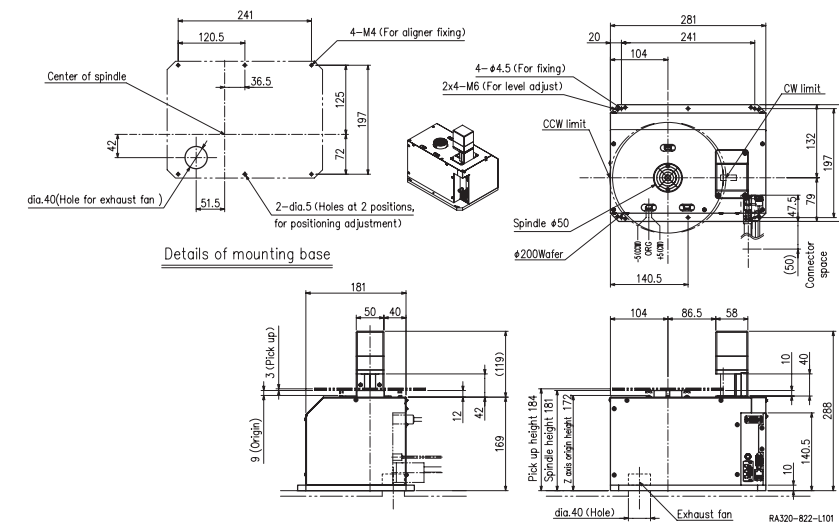
Note 1: This is the processing time interval of standard accuracy, and changes according to the kind of sensor, wafer size, and required accuracy.

Outline dimensions

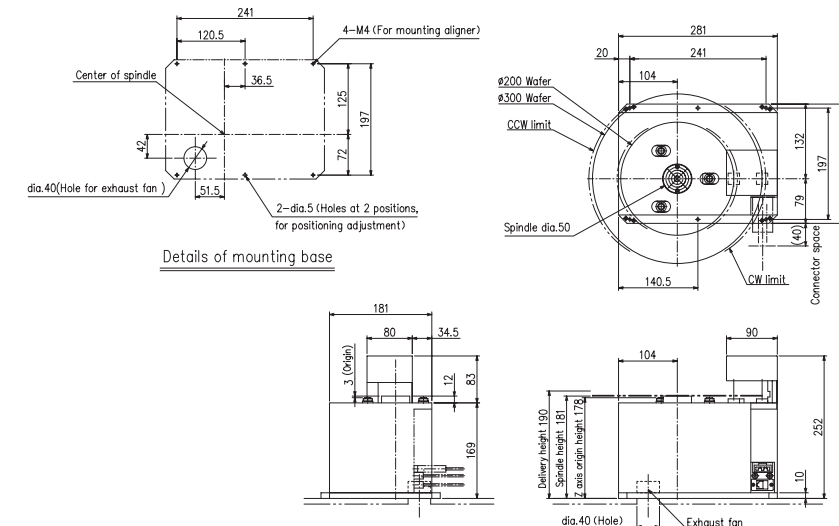
RA320-C22-L



RA320-822-L



RA320-822-W



RA320-622-L

